



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Khan *et al.*

Appl. No. 09/783,034

Filed: February 15, 2001

For: **Die-Down Ball Grid Array
Package with Die-Attached Heat
Spreader and Method for Making
the Same (As Amended)**

Confirmation No.: 5713

Art Unit: 2826

Examiner: Andujar, L.

Atty. Docket: 1875.0210000

Amendment And Reply Under 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In reply to the Office Action dated **March 26, 2002**, (PTO Prosecution File Wrapper Paper No. 2), Applicants submit the following Amendment and Remarks. This Amendment is provided in the following format:

- (A) A clean version of each replacement paragraph/section/claim along with clear instructions for entry;
- (B) Starting on a separate page, appropriate remarks and arguments; 37 C.F.R. § 1.121 and MPEP 714; and
- (C) Starting on a separate page, a marked-up version entitled: "Version with markings to show changes made."

It is not believed that extensions of time or fees for net addition of claims are required beyond those that may otherwise be provided for in documents accompanying this paper. However, if additional extensions of time are necessary to prevent

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02 FC:102 168.00 DP

abandonment of this application, then such extensions of time are hereby petitioned under 37 C.F.R. § 1.136(a), and any fees required therefor (including fees for net addition of claims) are hereby authorized to be charged to our Deposit Account No. 19-0036.

Amendments

In the Title:

Please substitute the following Title of the Invention for the pending Title of the Invention:

Die-Down Ball Grid Array Package with Die-Attached Heat Spreader and Method for Making the Same.

In the Claims:

Please amend claims 1-15, 17-25, 27-32, and 34-36 as follows:

1.(Amended) A ball grid array (BGA) package, comprising:
a stiffener;

a substrate that has a first surface and a second surface, wherein said substrate has a central window-shaped aperture that extends through said substrate from said first surface of said substrate to said second surface of said substrate, wherein said first